

Problem1: Describe how MOSFET works, including 4 regions talked in the class.

Main point: list 4 regions (Cutoff, Subthreshold, Triode, Saturation), and give the working conditions for those 4 region and explain it in relative detail, follow the lecture notes.

Note: There is a subtle difference from what we talked Accumulation, Depletion, Weak/Strong Inversion in the MOS cap. Don't mixed those two models up, although they do have strong relationships.

Problem 5.2

Ans: From Eq (5.8), the number of acceptor atoms in the substrate

$$N_A = n_i \exp(|\phi_F| q/KT) = 8.354 \times 10^{14} \text{ atoms/cm}^3$$

Use Eq (5.20),

$$C'_{ox} = (2 \times q \epsilon_{si} N_A)^{0.5} / \lambda = 369.72 \text{ aF}/\mu\text{m}^2$$

The KP of this n-channel MOSFET is

$$KP = \mu_n \times C'_{ox} = 550 \text{ cm}^2/\text{V} \times 369.72 \text{ aF}/\mu\text{m}^2 = 20.33 \mu\text{A}/\text{V}^2$$

From Eq. (5.36), $\beta = KP \times W/L = 20.33 \times 10/2 = 101.56$

From Eq. (5.21), $V_{THN} = 0.8\text{V} + 0.45 \times ((.57+1)^{0.5} - (.57)^{0.5}) = 1.024\text{V}$

Since $V_{DS} > V_{GS} - V_{THN}$ and $V_{GS} > V_{THN}$, the MOSFET is operated in saturation region.

With $\lambda=0$, use Eq (5.39),

$$I_D = \beta (V_{GS} - V_{THN})^2 / 2 \approx 48.4 \mu\text{A}$$

If use CN20 process, the C'_{ox} is $800 \text{ aF}/\mu\text{m}^2$, and $KP = 44 \mu\text{A}/\text{V}^2$, $I_D = 104.78 \mu\text{A}$

For $V_{sb}=0\text{V}$

Clearly, $V_{thn}=V_{thn0}=0.8\text{V}$, and $V_{gs}-V_{thn}=2-0.8=1.1\text{V}$, $V_{ds}=1.1\text{V}$, so $V_{ds} < V_{gs}-V_{thn}$, it works in Triode region, so we need to use the equation of I_{ds} in Triode region to calculate I_{ds} , and the result is $I_{ds}=72.7\mu\text{A}$.

Problem 5.5

$$C'_{ox} = \epsilon_{ox} / TOX = (8.85 \times 3.97 \text{ aF}/\mu\text{m}) / (400 \times 10^{-10} \text{ m}) = 878.4 \text{ aF}/\mu\text{m}^2$$

Problem 5.8

The electrostatic potential of the oxide semiconductor interface when $V_{gs} = V_{thn0}$

$$\text{is: } \phi_s = -\phi_F = \frac{kT}{q} \ln \frac{N_A}{N_i}$$

Where N_A is the number of acceptor atoms in the substrate, N_i is the intrinsic carrier concentration of silicon.

Problem 5.13

Since every MOSFET shown in Figure P5.13 has the same V_{DS} , V_{GS} , KP , L and V_{THN} , the current flowing through every MOSFET is

$$I_{Dn} = (KP \times W_n \times /L) \times [(V_{GS} - V_{THN})V_{DS} - V_{DS}^2/2], n = 1, 2, \dots, N$$

(neglect the body effect and for both triode and saturation region, this equation is effective.)

Therefore, the total current from drain to source is

$$I_D = [KP \times (W_1 + W_2 + \dots + W_N) / L] \times [(V_{GS} - V_{THN})V_{DS} - V_{DS}^2/2]$$

This I-V characteristic is the same as one single MOSFET with a width equal to the sum of each individual MOSFET's width.

Problem 5.15

From Figure P5.14, we assume that both MOSFET are in the triode region. Neglecting the body effects,

$$1) \quad I_D \times L1 / (KP \times W) = (V_{gs1} - V_{thn}) V_{ds1} - V_{ds1}^2 / 2 = (V_g - V_{thn}) V1 - V1^2 / 2$$

$$2) \quad I_D \times L2 / (KP \times W) = (V_{gs2} - V_{thn}) V_{ds2} - V_{ds2}^2 / 2 \\ = (V_g - V_{thn} - V1) (Vd - V1) - (Vd - V1)^2 / 2$$

1)+2)

$$I_D \times (L2 + L1) / (KP \times W) = V_g Vd - V_{thn} Vd - Vd^2 / 2 = (V_g - V_{thn}) Vd - Vd^2 / 2$$

Re-arranging this equation,

$$I_D = [KP \times W / (L2 + L1)] \times [(V_{GS} - V_{THN})V_{DS} - V_{DS}^2/2]$$

From this equation, Figure P5.14 does behave as a single MOSFET with the length equal to the sum of the individual MOSFET's length.

Problem 5.19

For the Fig. P5.19, the layout of an n-channel MOSFET is equal to 5 MOSFETs, each with $W/L=4/25$, connected serially. Therefore, the device's width is $4 \mu\text{m}$ and length is $5 \times 25 = 125 \mu\text{m}$.

You could relate problem 5.15 with Problem 5.19, just like you could relate the layout example on the book Page 103 with the problem 5.13.